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INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	Applicant: Cem Basceri et al.	
	Filing Date: June 21, 2000	Group: Unknown

U.S. PATENT DOCUMENTS

**Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
<i>ca</i>	5,142,438	08/25/1992	Reinberg, A.R., et al.	361	313	11/15/91
<i>ca</i>	5,358,889	10/25/1994	Emesh, I.T., et al.	437	60	04/29/93
<i>ca</i>	5,910,880	06/08/1999	DeBoer, S.J., et al.	361	311	08/20/97
<i>ca</i>	5,969,983	10/19/1999	Thakur, R.P., et al.	365	149	03/01/99

FOREIGN PATENT DOCUMENTS

**Examiner Initial	Document Number	Date	Country	Class	Subclass	Translation Yes   No
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OTHER DOCUMENTS

(Including Author, Title, Date, Pertinent Pages, Etc.)

**Examiner Initial	(Including Author, Title, Date, Pertinent Pages, Etc.)
<i>ca</i>	Aoyama, T., et al., "Ultrathin Ta <sub>2</sub> O <sub>5</sub> Film Capacitor with Ru Bottom Electrode", <u>J. Electrochem. Soc.</u> , 145(8), pp. 2961-2364, (1998)
<i>ca</i>	Kishiro, K., et al., "Structure and Electrical Properties of Thin Ta <sub>2</sub> O <sub>5</sub> Deposited on Metal Electrodes", <u>Jpn. J. Appl. Phys.</u> , 37, pp. 1336-1339, (1998)
<i>ca</i>	Lin, J., et al., "Ta <sub>2</sub> O <sub>5</sub> thin films with exceptionally high dielectric constant", <u>Applied Physics Letters</u> , pp. 2370-2372, (1999)
<i>ca</i>	Nakamura, S., et al., "Embedded DRAM Technology compatible to the 0.13 micrometer high-speed Logics by using Ru pillars in cell capacitor and peripheral vias", <u>IEDM</u> , pp. 1029-1031, (1998)

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\*Substitute Disclosure Statement Form (PTO-1449)

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